

SMALL SIGNAL SCHOTTKY DIODE

BAT 49

80V 3.0A

FEATURES

- Small foot print, surface mountable
- Very low forward voltage drop
- · High frequency operation
- Guard ring for enhanced ruggedness and long term reliability

DESCRIPTION

General purpose metal to silicon diode featuring very low turn-on voltage and fast switching. This device has integrated protection against excessive voltage such as electrostatic discharges.



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit	
V _{RRM}	Repetitive Peak Reverse Voltage	80	V	
I _F	Forward Continuous Current*	T _a = 70 °C	500	mA
I _{FRM}	Repetitive Peak Forward Current*	$\begin{array}{l} t_p = 1s \\ \delta \leq 0.5 \end{array}$	3	А
I _{FSM}	Surge non Repetitive Forward Current*	$t_p \leq 10 ms$	10	А
T _{stg} T _j	Storage and Junction Temperature Range	- 65 to 150 - 65 to 125	° S S	
ΤL	Maximum Lead Temperature for Soldering during 10s at 4mm from Case		230	°C

THERMAL RESISTANCE

Symbol	Test Conditions	Value	Unit
R _{th(j-a)}	Junction-ambient*	110	°C/W

ELECTRICAL CHARACTERISTICS

STATIC CHARACTERISTICS

Symbol		Test Conditions	Min.	Тур.	Max.	Unit
I _R * *	T _j = 25°C	V _R = 80V			200	μA
V _F * *	T _j = 25°C	I _F = 10mA			0.32	V
	T _j = 25°C	I _F = 100mA			0.42	
	T _j = 25°C	$I_F = 1A$			1	

DYNAMIC CHARACTERISTICS

Symbol	Test Conditions			Min.	Тур.	Max.	Unit
С	T _j = 25°C	f = 1MHz	$V_R = 0V$		120		pF
			$V_R = 5V$		35		



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Figure 3. Reverse current versus junction temperature.



Figure 4. Reverse current versus V_{RRM} in per cent.



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Figure 5. Capacitance C versus reverse applied voltage V_R (typical values).



Figure 6. Surge non repetitive forward current for a rectangular pulse with t \leq 10 ms.



Figure 7. Surge non repetitive forward current versus number of cycles.



